# **K2G General-Purpose (GP) Evaluation Module (EVM) Quick Start Guide**



Welcome to the K2G General-Purpose (GP) Evaluation Module (EVM) Quick Start Guide. This guide is designed to help you through the initial setup of the K2G GP EVM. The K2G GP EVM contains the following:

# Hardware

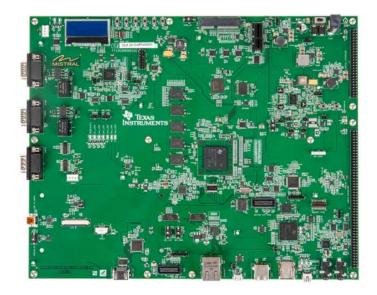
- K2G KeyStone<sup>™</sup>-based SoC XDA1030 with ARM<sup>®</sup> Cortex<sup>®</sup>-A15 @ 600 MHz and C66x DSP @ 600 MHz
- 2-GByte DDR3L with ECC
- 2-Gbit NAND Flash
- 128-Mbit SPI NOR Flash
- 512-Mbit QSPI
- 128-kByte I<sup>2</sup>C EEPROM
- 16-GB eMMC
- Micro-SD-card slot
- Gigabit Ethernet
- PCIe card slot
- HDMI transmitter
- Audio codec AIC3106
- COM8 connector
- DCAN and MLB connectors
- USB host and USB dual-role
- Audio expansion and serial expansion headers
- Board Management Controller (BMC) for board management features like system status and boot mode control
- On-board XDS200 emulator and MIPI 60-pin connector for external emulator
- RS-232 DB9 connector

# Printed document

- K2G GP EVM Quick Start Guide (this document)

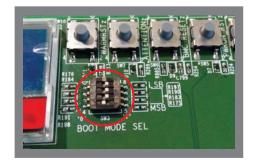
# Miscellaneous

- USB Mini B to A plug type cable
- USB Micro B to A plug type cable
- USB Micro B to A socket type cable
- Ethernet cable
- Female-to-female DB9 serial RS-232 cable
- μSD card 32 GB, memory card reader and μSD-to-SD adapter
- Power cable
- Connection for LCD display with capacitive touch (display is sold separately)

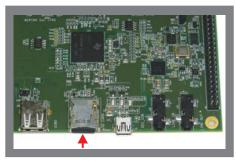


# Instructions to boot out-of-box demonstration

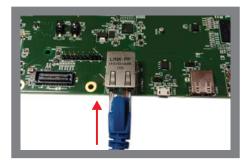
Note: For TI RTOS users, please refer to the RTOS Getting Started Guide at http://processors.wiki.ti.com/index.php/Processor SDK RTOS Getting Started Guide



Set DIP switch (SW3) to '0111' (MSB first) as shown to select MMC/SD boot mode.



Insert the SD card as shown.



Using the Ethernet cable, connect the EVM to a network containing a PC running a DHCP server.



Connect 12V power cable to the DC jack (J3). Slide the power switch SW1 to the "ON" position marked on the silkscreen. LED LD9 will light up.



Note the IP address
displayed on LCD screen.
Enter this address into a web
browser connected to the
same network as the EVM.



The host PC will connect to the EVM, and the demonstration may now be run.



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